



**Thank you very much for visiting SEMICON Japan 2025**, held from December 17 to 19, 2025.

We would also like to express our sincere appreciation to everyone who took the time to visit our booth.

We are truly grateful for the strong interest and positive feedback we received regarding our exhibition equipment supporting **Panel Level Packaging (PLP)**.

Your valuable comments and insightful questions have been a great encouragement to us, and we will continue striving to provide advanced solutions that support the further implementation and commercialization of PLP technology.

If you have any questions, comments, or require further information regarding the products introduced during the exhibition, or if you would like more details about our demonstration, please do not hesitate to contact us at any time.

We sincerely appreciate your continued support and look forward to working with you in the future.

